### 503476931 09/14/2015

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3523556

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chun-Hsien Wu	09/09/2015
Chen-Hsien Hsu	09/09/2015
Wei-Jen Wang	09/09/2015
Chien-Fu Chen	09/09/2015
Chien-Hung Chen	09/09/2015

#### RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14852635

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	NAUP2531USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	09/14/2015

Total Attachments: 10 source=2354211#page1.tif source=2354211#page2.tif source=2354211#page3.tif

PATENT 503476931 REEL: 036548 FRAME: 0890



PATENT REEL: 036548 FRAME: 0891

### Title of invention:

### SEMICONDUCTOR LAYOUT STRUCTURE AND DESIGNING METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on, c	or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be mad	de by me.	
I believe that I am the original inventapplication.	or or an original joint inventor o	of a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTRO	ONICS having a postal addre	ss of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, H	Isin-Chu City 300, Taiwan, I	R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		1.00), the receipt of which is here	by
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements tion and, in and to, all Letters F any continuations, continuatio	s which are disclosed in the Patent to be obtained for said on-in-part, divisions, renewals,	E
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbr n this assignment;	rance has been or will be made o	r
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent an stify as to the same in any inte	nd legal equivalents as may be rference, litigation proceeding	·
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	olication, said invention and said ecessary or desirable to carry or	d Letters Patent and said out the proposes thereof.	signing)
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 1 of 10

F#NPO-P0002E-US1201 DSC0-104U006852

NPO#NAU-P2531-USA:0

**PATENT** REEL: 036548 FRAME: 0892 LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: C

Chun-Hsien Wu

Date:

SEP 0 9 2015

Signature:

chun-Hsien Wu

Page 2 of 10

F#NPO-P0002E-US1201 DSC0-104U006852

NPO#NAU-P2531-USA:0

### Title of Invention:

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☐ PCT international application	n number	filed on	•
The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	l false statement made in this de isonment of not more than five (5	claration is punishable y years, or both.	
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Par r any continuations, continuation-	which are disclosed in the tent to be obtained for said in-part, divisions, renewals	IEE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	nce has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	ats
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	olication, said invention and said lacessary or desirable to carry out	Letters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for each ad-	naming the entire ditional inventor.	

Page 3 of 10

NPO#NAU-P2531-USA:0 CUST#UMCD-2015-0286

LEGAL NAI	ME OF INVENTOR(ASSIGN	OR)			
Inventor:	Chen-Hsien Hsu		Date:	SEP 0 9 2015	
Signature:	Chen-Hsten	Hsu			

Page 4 of 10

NPO#NAU-P2531-USA:0 CUST#UMCD-2015-0286

## Title of Invention: SEMICONDUCTOR LAYOUT STRUCTURE AND DESIGNING METHOD THEREOF

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☑ The attached application, or				
☐ United States application nu	mber	filed	on	, or
☐ PCT international application	n number	fil	ed on	
The above-identified application was	made or authorize	d to be made by me	***************************************	
I believe that I am the original invent application.	or or an original join	t inventor of a claim	ed invention in	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement ma isonment of not mo	ade in this declaration re than five (5) years	n is punishab s, or both.	le
In consideration of the payment by	UNITED MICRO	ELECTRONICS	having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industri	al Park, Hsin-Ch	u City 300,	Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an			receipt of wh	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all imp tion and, in and to, a r any continuations,	provements which a all Letters Patent to continuation-in-part,	re disclosed ir be obtained fo divisions, ren	n the or said newals.
l hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement on this assignment;	or encumbrance has	s been or will t	oe made or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letter stify as to the same	s Patent and legal e in any interference,	quivalents as litigation prod	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	lication, said invent cessary or desirable	ion and said Letters e to carry out the pro	Patent and sa	aid f. _(Date of signing 
Note: An application data sheet (PTC				

Page 5 of 10

NPO#NAU-P2531-USA:0 CUST#UMCD-2015-0286

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Wei-Jen Wang	Date:	SEP 0 9 2015	
Signature:	Wei-Jen, Wang			_

Page 6 of 10

### Title of Invention:

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The above-identified application was	s made or authorized to be made	by me.	***************************************	
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(referred to as "ASSIGNEE"below) t acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the re	eceipt of whi	ch is hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, a	ind to any and all improvements varion and, in and to, all Letters Pa r any continuations, continuation	vhich are itent to be -in-part, di	disclosed in obtained fo visions, rene	the r said ewals.
I hereby covenant that no assignme entered into which would conflict wit	nt, sale, agreement or encumbra h this assignment;	nce has b	een or will b	e made or
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representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be not IN WINTNESS WHEREOF, I have h	plication, said invention and said acessary or desirable to carry out	Letters Pa	itent and sa ses thereof	id (Date of signing) -
Note: An application data sheet (PTo inventive entity, must accompany the				

Page 7 of 10

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Chien-Fu Chen	Date:	SEP 0 9 2015	
Signature:	Chien-Fu Chen			

Page 8 of 10

### Title of Invention:

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Page 9 of 10

NPO#NAU-P2531-USA:0 CUST#UMCD-2015-0286

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chien-Hung Chen	Date:	SEP 0 9 2015		
Signature:	Chlen-Hung Chen				

Page 10 of 10

NPO#NAU-P2531-USA:0 CUST#UMCD-2015-0286

**RECORDED: 09/14/2015** 

F#NPO-P0002E-US1201 DSC0-104U006852

PATENT REEL: 036548 FRAME: 0901